

ABSTRACT OF THE DISCLOSURE

An electronic unit includes a module in which a semiconductor device is attached on the bottom of a circuit board and which has lands provided on the bottom of the circuit board, and a printed circuit board on which the module is mounted, the printed circuit board having a hole in a position facing the semiconductor device and having electrical conductors to which the lands are soldered. The module is mounted on the printed circuit board by soldering the lands to the electrical conductors while the semiconductor device is disposed in the hole. Accordingly, the electronic unit is smaller in height than conventional electronic units. Such a structure allows the module to be surface-mounted on the printed circuit board with solder paste, and thus high productivity of the electronic unit can be achieved.